



Material Content Data Sheet



Sales Product Name		BFR 360F H6327		Issued		20. July 2018		
MA#		MA000895772						
Package		PG-TSFP-3-1		Weight*		1.43 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.000	0.03		324	
	noble metal	gold	7440-57-5	0.002	0.13		1258	
	inorganic material	silicon	7440-21-3	0.013	0.93	1.09	9323	10905
leadframe	inorganic material	silicon	7440-21-3	0.000	0.01		80	
	non noble metal	titanium	7440-32-6	0.001	0.04		400	
	non noble metal	chromium	7440-47-3	0.002	0.12		1199	
	non noble metal	copper	7440-50-8	0.570	39.79	39.96	397855	399534
wire	noble metal	gold	7440-57-5	0.004	0.28	0.28	2751	2751
encapsulation	organic material	carbon black	1333-86-4	0.008	0.55		5458	
	plastics	epoxy resin	-	0.168	11.73		117345	
	inorganic material	silicondioxide	60676-86-0	0.607	42.29	54.57	422989	545792
leadfinish	non noble metal	tin	7440-31-5	0.034	2.36	2.36	23644	23644
plating	noble metal	silver	7440-22-4	0.025	1.74	1.74	17374	17374
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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